



SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL02C101JQ2ANNC
- Description : CAP, 100pF, 6.3V, ±5%, C0G, 01005

A. Samsung Part Number

			<u>CL</u>	<u>02</u>	<u>C</u>	<u>101</u>	<u>J</u>	<u>Q</u>	<u>2</u>	<u>A</u>	N	<u>N</u>	<u>C</u>
			1	2	3	4	5	6	1	8	9	10	1
1	Series	Samsung	g Multi-la	iyer C	eram	ic Cap	acito	r					
2	Size	01005	(inch co	ode)		L:	0.4	± 0.0)2	mm		W:	0.2 ± 0.02 mm
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Pd
4	Capacitance	100	рF					Tern	ninat	tion			Ag
5	Capacitance	±5	%					Plati	ng				Sn 100% (Pb Free)
	tolerance						9	Proc	luct				Normal
6	Rated Voltage	6.3	V				10	Spe	cial				Reserved for future use
1	Thickness	0.2	± 0.02	mm			1	Pacl	kagir	ng			Cardboard Type, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms						
Q	1000 min							
Insulation	10,000Mohm or 500Mohm · <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×20)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)							
Adhesive Strength	No peeling shall be occur on the	100g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 200 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 350 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^\circ\!\!\!\mathrm{C}$					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\!\mathbb{C}$, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.